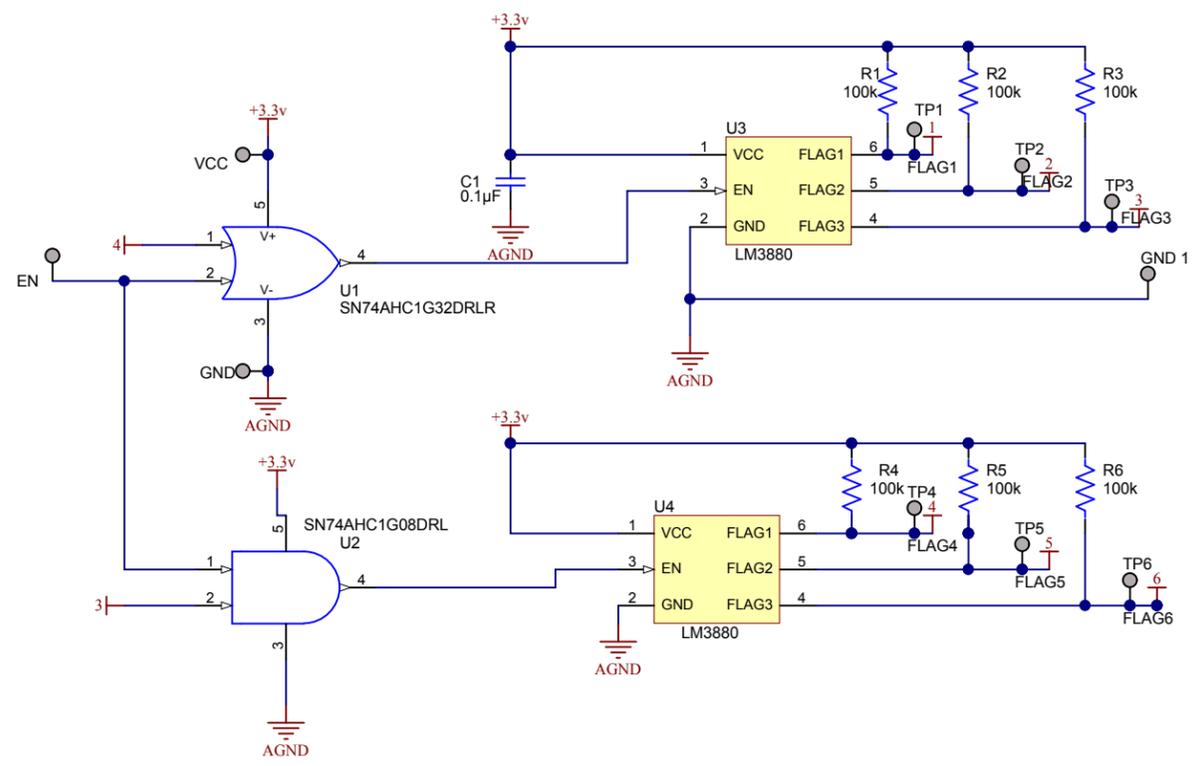


DNP FID1
 DNP FID2
 DNP FID3

PCB Number: PMP10711
 PCB Rev: 1

PCB LOGO
 Texas Instruments

PCB LOGO
 Pb-Free Symbol



ZZ2
 Assembly Note
 These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
 Assembly Note
 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
 Assembly Note
 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Orderable: N/A	Designed for: Public Release	Mod. Date: 11/2/2015
TID #: PMP10711	Project Title: 6 Channel Sequencer w/ Fixed Delay	
Number: PMP10711	Rev: 1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 1
Drawn By:	File: 6ChanSeqTIDesign_TID_Hardware.SchDoc	Size: B
Engineer: Cecilia Reyes	Contact: http://www.ti.com/support	



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